

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hironori FUKAYA</td> <td>08/26/2010</td> </tr> <tr> <td>Yuzo SHIMOBEPPI</td> <td>08/26/2010</td> </tr> <tr> <td>Kazuhiro YOSHIMOTO</td> <td>08/26/2010</td> </tr> <tr> <td>Kazuo TESHIROGI</td> <td>08/26/2010</td> </tr> <tr> <td>Kazuyuki URAGOU</td> <td>08/30/2010</td> </tr> <tr> <td>Mika SAKAMOTO</td> <td>08/30/2010</td> </tr> <tr> <td>Masaya TAZAWA</td> <td>08/26/2010</td> </tr> </tbody> </table>		Name	Execution Date	Hironori FUKAYA	08/26/2010	Yuzo SHIMOBEPPI	08/26/2010	Kazuhiro YOSHIMOTO	08/26/2010	Kazuo TESHIROGI	08/26/2010	Kazuyuki URAGOU	08/30/2010	Mika SAKAMOTO	08/30/2010	Masaya TAZAWA	08/26/2010
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RECEIVING PARTY DATA																	
Name:	FUJITSU SEMICONDUCTOR LIMITED																
Street Address:	2-10-23 Shin-Yokohama, Kohoku-ku																
City:	Yokohama-shi, Kanagawa																
State/Country:	JAPAN																
Postal Code:	222-0033																
PROPERTY NUMBERS Total: 1																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12874659</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12874659												
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CORRESPONDENCE DATA																	
Fax Number:	(703)535-8420																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
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CH \$40.00 12874659

501409838

PATENT
REEL: 025658 FRAME: 0807

NAME OF SUBMITTER:

Tiep H. Nguyen

Total Attachments: 6

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U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by
(Insert Name(s) & Address(es) of ASSIGNEE(S))

Fujitsu Semiconductor Limited

2-10-23 Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033 Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
(Title of Invention)

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND SURFACE PROTECTIVE TAPE

relating to International Patent Application PCT/JP _____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on _____ *(Insert date of execution of application, if not concurrent)*

(b) filed on Sep 2, 2010

Serial No. 12/874,659

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

1) <u>Hironori Fukaya</u> <i>(Signature)</i>	<u>Hironori FUKAYA</u> <i>(Type Name)</i>	<u>Aug. 26, 2010</u> <i>(Date)</i>
2) <u>Yuzo Shimobeppu</u> <i>(Signature)</i>	<u>Yuzo SHIMOBEPPI</u> <i>(Type Name)</i>	<u>Aug. 26, 2010</u> <i>(Date)</i>
3) <u>Kazuhiro Yoshimoto</u> <i>(Signature)</i>	<u>Kazuhiro YOSHIMOTO</u> <i>(Type Name)</i>	<u>Aug. 26, 2010</u> <i>(Date)</i>
4) _____ <i>(Signature)</i>	<u>Kazuo TESHIROGI</u> <i>(Type Name)</i>	_____ <i>(Date)</i>

5)	<hr/> <i>(Signature)</i>	Kazuyuki URAGOU <hr/> <i>(Type Name)</i>	<hr/> <i>(Date)</i>
6)	<hr/> <i>(Signature)</i>	Mika SAKAMOTO <hr/> <i>(Type Name)</i>	<hr/> <i>(Date)</i>
7)	<i>Masaya Tazawa</i> <hr/> <i>(Signature)</i>	Masaya TAZAWA <hr/> <i>(Type Name)</i>	<i>Aug. 26 - 2010</i> <hr/> <i>(Date)</i>

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(b) filed on Sep 2, 2010

Serial No. 12 / 874,659

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	(Signature)	(Type Name)	(Date)
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5) Kazuyuki Uragou
(Signature)

Kazuyuki URAGOU
(Type Name)

Aug. 30, 2010
(Date)

6) mika sakamoto
(Signature)

Mika SAKAMOTO
(Type Name)

Aug. 30, 2010
(Date)

7) _____
(Signature)

Masaya TAZAWA
(Type Name)

(Date)